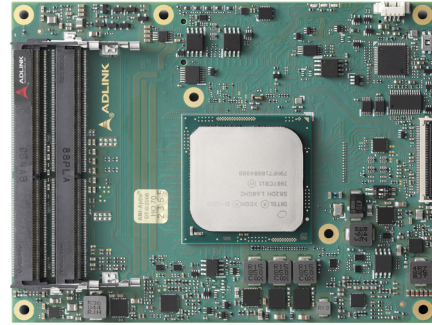


Express-BD74

COM Express Basic Size Type 7 Module with Intel® Xeon® D SoC and 4 SODIMMs

Features

- 4 SO-DIMMs, up to 128GB dual channel DDR4 at 1866/2133/2400MHz ECC (dependent on SoC SKU)
- Intel® Xeon® D SoC (up to 16 cores)
- Two 10G Ethernet and NC-SI support
- Up to 32 PCIe lanes (24x Gen3, 8x Gen2)
- GbE, two SATA 6 Gb/s, four USB 3.0/2.0
- Supports Smart Embedded Management Agent (SEMA®) functions
- Extreme Rugged operating temperature: -40°C to +85°C (build option with selected SoC SKU)



Specifications

Core System

CPU

Intel® Xeon® D and Pentium® D SoC, 14nm process (formerly "Broadwell-DE")

Xeon® D1559 1.6/2.1GHz 18MB, 45W (12C) (eTEMP)

Xeon® D1539 1.6/2.2GHz 12MB, 35W (8C) (eTEMP)

Xeon® D1577 1.3/2.1GHz 24MB, 45W (16C)

Xeon® D1548 2.0/2.6GHz 12MB, 45W (8C)

Note: SKUs not listed above and D1577/D1559 may be supported on a project basis. please contact your ADLINK representative.

Supports: Intel® VT (including VT-x, VT-d, VT-x with Extended Page Tables), Intel® HT Technology, Intel® SSE4.2, Intel® 64 Architecture, Intel® Turbo Boost Technology 2.0, Intel® AVX2, Intel® TSX-NI, Intel® Platform Protection Technology with Intel® TXT, Execute Disable Bit, Intel® Data Protection Technology with Intel® Secure Key, Intel® AES-NI

Note: Availability of features may vary between processor SKUs.

Memory

Dual channel 1867/2133/2400 MHz DDR4 ECC memory in four SODIMM sockets (two on top, two on bottom), up to 128GB (dependent on SoC SKU)

Note: Only D1548 supports up to 2400 MHz

Embedded BIOS

AMI EFI with CMOS backup in 16MB SPI BIOS

Cache

24MB for D1577

18MB for D1559

12MB for D1548/D1539

Expansion Busses

PCIe x16 or 2 PCIe x8 or 4 PCIe x4 (Gen3)

8 PCIe lanes (Gen3): AB connector, Lanes 8-15

6 PCIe lanes (Gen2): AB connector, Lanes 0/1/2/3/4/5

Up 2 PCIe lanes (Gen2): CD connector, Lanes 6/7

LPC bus, SMBus (system), I²C (user)

Note: PCI Express lane 7 support in place of GbE

SEMA Board Controller

Supports: Voltage/current monitoring, power sequence debug support, AT/ATX mode control, logistics and forensic information, flat panel control, general purpose I²C, Failsafe BIOS (dual BIOS, opt. support), watchdog timer and fan control

Debug Headers

40-pin multipurpose flat cable connector for use with DB-40 debug module providing BIOS POST code LED, BMC access, SPI BIOS flashing, power testpoints, debug LEDs

10G Ethernet

Intel® MAC/Controller

Intel® 10G Ethernet Controller integrated in SoC

10G Interface

2x 10GBASE-KR

10G Sideband Signals

10G_INT

10G_PHY_MDIO/MDC & SDA/SCL

10G_PHY_CAP

10G_PHY_RST

10G_LED_I2C

10G_SFP_I2C

10G_SDP

NC-SI

NC-SI supported on AB connector,

connect to GbE controller

Ethernet

Intel® MAC/PHY: Intel® Ethernet Connection i210

Interface: 10/100/1000 GbE connection

Multi I/O and Storage

USB: 4x USB 3.0/2.0 (USB 0, 1, 2, 3)

SATA: 2x SATA 6Gb/s (SATA0,1)

Serial: 2 UART ports with console redirection

GPIO: 4 GPO and 4 GPI

Super I/O

Supported on carrier if needed (standard support for W83627DHG-P)

Specifications

• TPM

Chipset: Infineon
Type: TPM 2.0

• Power

Standard Input: ATX: 12V±5%, 5Vsb ±5%; AT: 12V±5%
Wide Input: ATX: 8.5-20V, 5Vsb ±5%; AT: 8.5-20V
Management: ACPI 5.0 compliant, Smart Battery support
Power States: C1-C6, S0, S1, S3, S4, S5, S5 ECO mode (Wake-on-USB S3/S4, WOL S3/S4/S5)
ECO mode: Supports deep S5 mode for power saving

• Operating Systems

Standard Support

Windows 10 (64-bit)
Windows Server 2012 (64-bit)
Windows 7 (64-bit)
Linux (64-bit)

Extended Support (BSP)

Linux (64-bit)

• Mechanical and Environmental

Form Factor: PICMG COM.0 Rev 3.0, Type 7
Dimension: Basic size: 125 mm x 95 mm

Operating Temperature

Standard: 0°C to 60°C
Extreme Rugged: -45°C to +85°C (build option, standard voltage only)
Note: Extreme Rugged availability dependent on SoC SKU

Humidity

5-90% RH operating, non-condensing
5-95% RH storage (and operating with conformal coating)

Shock and Vibration

IEC 60068-2-64 and IEC-60068-2-27
MIL-STD-202F, Method 213B, Table 213-I, Condition A and Method 214A, Table 214-I, Condition D

HALT

Thermal Stress, Vibration Stress, Thermal Shock and Combined Test

Note: "build option" indicates an alternative BOM configuration to support additional or alternative functions that are not available on the standard product.
Be aware that these "build option" part numbers will need to be newly created and this will result in production lead times.

Functional Diagram

